

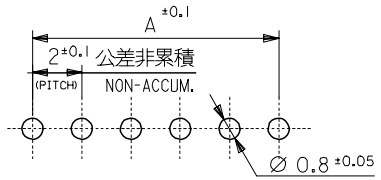
注記 NOTES

1. 嵌合相手: 51065 シリーズ
MATE WITH: 51065 SERIES
2. 材質 MATERIAL
ウエハー: 66ナイロン, UL94V-0
WAFER: 66NYLON, UL94V-0
ピン: 黄銅, 金メッキ
PIN: BRASS, GOLD (Au) PLATING
3. キングは下記表の位置及び形状に付加のこと。2極はキング無し。
KINK TO BE APPLIED AS FOLLOWS,
2 CIRCUIT HAS NO KINK.

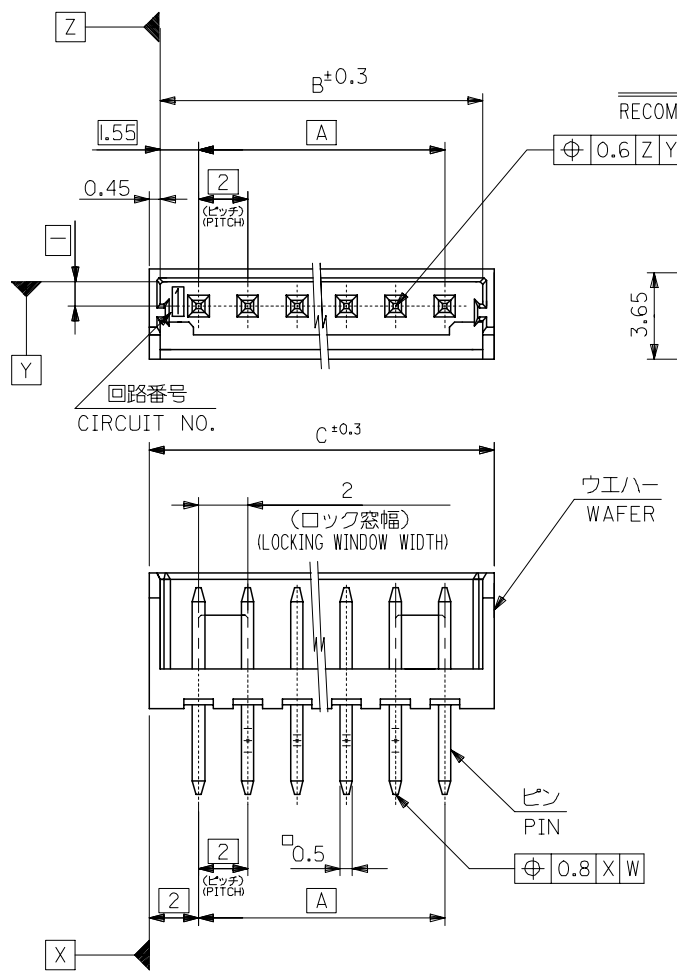
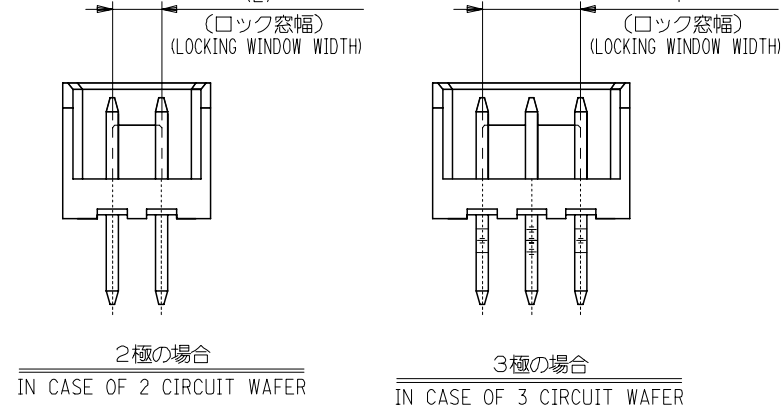
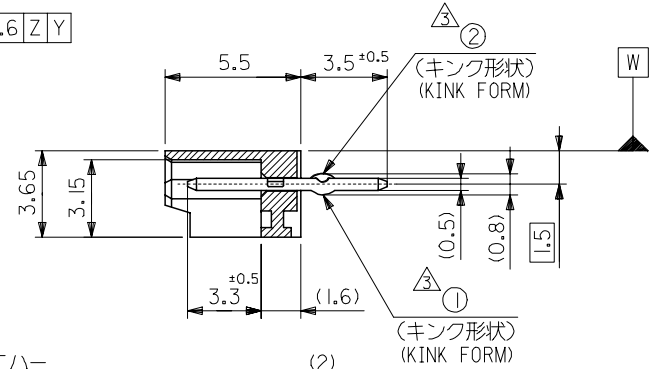
| 極数 CKT | 回路番号 CKT NO. | 回路番号 | | | | | | | |
|--------|-----------------|------|---|---|---|---|-----|-----|---|
| | | 1 | 2 | 3 | 4 | 5 | N-2 | N-1 | N |
| 6 極以上 | MORE THAN 6 CKT | — | ① | ② | — | — | ② | ① | — |
| 5 極 | 5 CKT | ① | ② | — | ② | ① | | | |
| 4 極 | 4 CKT | ① | ② | ② | ① | | | | |
| 3 極 | 3 CKT | ① | ② | ① | | | | | |

4. 本製品は、53253-**70の金メッキ品です。
THIS PRODUCT IS AU PLATING OF 53253-**70.
5. 梱包仕様 PACKAGING
502603-**70 トレー TRAY
502603-**50 ポリ袋 POLYBAG

| | | | | | |
|----|------|----|--------------|--------------|----|
| 32 | 31.1 | 28 | 502603-1550 | 502603-1570 | 15 |
| 30 | 29.1 | 26 | -1450 | -1470 | 14 |
| 28 | 27.1 | 24 | -1350 | -1370 | 13 |
| 26 | 25.1 | 22 | -1250 | -1270 | 12 |
| 24 | 23.1 | 20 | -1150 | -1170 | 11 |
| 22 | 21.1 | 18 | -1050 | -1070 | 10 |
| 20 | 19.1 | 16 | -0950 | -0970 | 9 |
| 18 | 17.1 | 14 | -0850 | -0870 | 8 |
| 16 | 15.1 | 12 | -0750 | -0770 | 7 |
| 14 | 13.1 | 10 | -0650 | -0670 | 6 |
| 12 | 11.1 | 8 | -0550 | -0570 | 5 |
| 10 | 9.1 | 6 | -0450 | -0470 | 4 |
| 8 | 7.1 | 4 | -0350 | -0370 | 3 |
| 6 | 5.1 | 2 | 502603-0250 | 502603-0270 | 2 |
| C | B | A | MATERIAL NO. | MATERIAL NO. | 極数 |
| | | | MODEL NO. | MODEL NO. | |



基板取付穴寸法 (参考) (t=1.6)
RECOMMENDED P.C. BOARD HOLE DIM. (REFERENCE)



| | | | | | | | |
|---|---------------------------------------|-----------------------|----------------------------|---------------------------|---|------------------------|------------------------|
| RELEASED EC NO: J2007-2775 DRWN: MAEDA CHK: NUKITA APPR: NUKITA 2007/04/04 2007/04/06 2007/04/06 | GENERAL TOLERANCES (UNLESS SPECIFIED) | | DIMENSION STYLE MM ONLY | | SCALE 5:1 | DESIGN UNITS METRIC | THIRD ANGLE PROJECTION |
| | 10 UNDER | ±0.2 | DRAWN BY YMAEDA | | TITLE NEW 2.0 WIRE TO BOARD CONN. WAFER ASSY (ST.) -LEAD FREE- | | |
| | 10 OVER 30 UNDER | ±0.25 | DATE 2007/03/30 | | MOLEX INCORPORATED | | |
| | 30 OVER | ±0.3 | CHECKED BY KTOYOTA | | | | |
| | ANGULAR | ±3 ° | DATE 2007/03/30 | | DOCUMENT NO. SD-502603-001 | | |
| DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS | | APPROVED BY NUKITA | | MATERIAL NO. SEE CHART | | SHEET NO. 1 OF 1 | |